Filename: PMP9480_BOM.xls
Variant: None
Generated: 11/21/2014 3:40:00 PM

PMP9480

Designator	Description	Manufacturer	PartNumber	Quantity
!PCB1	Printed Circuit Board	Any	PMP9480	1
C1	CAP, CERM, 330 pF, 100 V, +/- 10%, X7R, 0603	MuRata	GRM188R72A331KA01D	1
C2, C5	CAP, CERM, 10 pF, 100 V, +/- 5%, C0G/NP0, 0603	MuRata	GRM1885C2A100JA01D	2
C3, C4	CAP, CERM, 0.1 µF, 50 V, +/- 10%, X7R, 0805	Taiyo Yuden	UMK212B7104KG-T	2
C6	CAP, CERM, 2200 pF, 2000 V, +/- 10%, X7R, 1812	TDK	C4532X7R3D222K	1
C7, C8, C9	CAP, CERM, 4.7uF, 25V, +/-20%, X7R, 0805	TDK Corporation	CGA4J1X7R1E475M125AC	3
C10	CAP, CERM, 1000 pF, 100 V, +/- 10%, X7R, 0603	AVX	06031C102KAT2A	1
C11	CAP, CERM, 0.01uF, 16V, +/-10%, X7R, 0603	MuRata	GRM188R71C103KA01D	1
C12	CAP, CERM, 0.01 µF, 100 V, +/- 10%, X7R, 0603	AVX	06031C103KAT2A	1
C13	CAP, CERM, 1uF, 16V, +/-10%, X5R, 0603	Kemet	C0603C105K4PACTU	1
C14	CAP, CERM, 10uF, 25V, +/-10%, X7R, 1206	MuRata	GRM31CR71E106KA12L	1
C15	CAP, CERM, 2.2 µF, 10 V, +/- 10%, X7R, 0805	Taiyo Yuden	LMK212B7225KG-T	1
C16, C17	CAP, CERM, 1 µF, 100 V, +/- 10%, X7R, 1812	Vishay-Vitramon	VJ1812Y105KBBAT4X	2
C18	CAP, CERM, 0.1 µF, 100 V, +/- 10%, X7R, 0805	Taiyo Yuden	HMK212B7104KG-T	1
D1	Diode, Schottky, 100V, 1A, PowerDI123	Diodes Inc.	DFLS1100-7	1
D2	Diode, Schottky, 45V, 0.1A, SOD-523	Diodes Inc.	SDM10U45-7-F	1
FID1, FID2, FID3, FID4, FID5, FID6	Fiducial mark. There is nothing to buy or mount.	N/A	N/A	6
H1, H2, H3, H4	Machine Screw, Round, #4-40 x 1/4, Nylon, Philips panhead	B&F Fastener Supply	NY PMS 440 0025 PH	4
H5, H6, H7, H8	Standoff, Hex, 0.5"L #4-40 Nylon	Keystone	1902C	4
J1, J2	Terminal Block, 6A, 3.5mm Pitch, 2-Pos, TH	On-Shore Technology	ED555/2DS	2
J3	AC Receptacle, 10A 250VAC	Qualtek Electronics Corporation	703W-00/54	1
J4, J5	Header, 100mil, 3x1, Gold, TH	Sullins Connector Solutions	PBC03SAAN	2
L1	Coupled inductor, 39uH, 1.9A, 0.142 ohm, +/-20%, SMD	Coilcraft	MSD1260-393MLB	1
LBL1	Thermal Transfer Printable Labels, 0.650" W x 0.200" H - 10,000 per roll	Brady	THT-14-423-10	1
R1, R2	RES, 12.0, 1%, 0.1 W, 0603	Yageo America	RC0603FR-0712RL	2
R3, R4	RES, 1.10 M, 1%, 0.25 W, 1206	Rohm	MCR18EZHF1104	2
R5	RES, 1.00 k, 1%, 0.25 W, 1206	Vishay-Dale	CRCW12061K00FKEA	1
R6	RES, 10.0 k, 1%, 0.1 W, 0603	Yageo America	RC0603FR-0710KL	1
R7	RES, 35.7 k, 1%, 0.1 W, 0603	Vishay-Dale	CRCW060335K7FKEA	1
R8	RES, 105 k, 1%, 0.1 W, 0603	Vishay-Dale	CRCW0603105KFKEA	1
R9	RES, 127 k, 0.5%, 0.1 W, 0603	Yageo America	RT0603DRE07127KL	1
R10	RES, 33.6 k, 0.1%, 0.1 W, 0603	Yageo America	RT0603BRD0733K6L	1
R11	RES, 10.0 k, 0.1%, 0.1 W, 0603	Yageo America	RT0603BRD0710KL	1
TP1, TP2, TP3, TP4, TP6, TP7, TP10, TP11	Terminal, Turret, TH, Double	Keystone	1502-2	8
TP5, TP9	Test Point, TH, Miniature, Red	Keystone	5000	2
TP8	Test Point, TH, Miniature, Black	Keystone	5001	1
U1	Fully-Differential Isolation Amplifier, DUB0008A	Texas Instruments	AMC1200BDUB	1
U2		Texas Instruments	LM5017MR	1

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